This design is intended to be used as an extension card (Booster-Pack) for LaunchPad.
Launchpad 3V can be powered by Booster Pack

Launchpad 5V0 can be powered by Booster Pack:

Launchpad 3V must be disconnected (see UG for details)

VCC_MCU_RF: default set to 1.8V

Vbatt: 2.5-3.6V

/GND_VBATT should be used for devices others than MSP430 from the Launchpad, this is a provision for future usage and for testing

GND_VBATT should be used for devices others than MSP430 from the Launchpad, this is a provision for future usage and for testing

Shunt by default between 2&4 on I2C(3.3V) is enabled, alternative option is GPIO control from MCU (Launchpad)

Jumpers to measure power cons of the PE protection + above GPIO control

Shunt by default between 2&3 so VCC_MCU is available (Connect to VSTOR to enable the buck converter), alternative option is GPIO control from MCU

Shunt by default between 2&3 so VCC_MCU is available (Connect to VSTOR to enable the buck converter), alternative option is GPIO control from MCU

Shunt by default between 2&4 so Charge Detection is enabled, can be changed to 2&1 to enable a GPIO from MCU (Launchpad) to control it (and reduce power)

Shunts set by default I2C device address to 0x0 for LP to read the BP TID design version

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